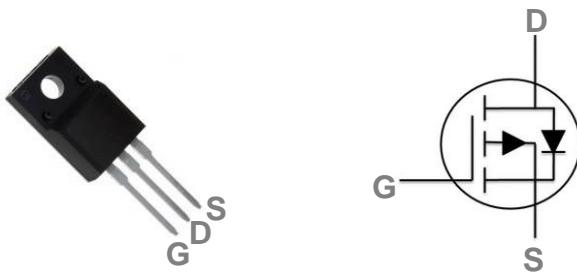


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO220F Pin Configuration



BVDSS	RDS(ON)	ID
-100V	140mΩ	-10A

### Features

- -100V,-10A, RDS(ON) 140mΩ@VGS = -10V
- VGS Guarantee  $\pm 25V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	-10	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	-6.5	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-40	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	48	W
	Power Dissipation – Derate above 25°C	0.38	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.6	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	---	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
		$V_{\text{DS}}=-80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-6\text{A}$	---	115	140	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-3\text{A}$	---	130	170	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	---	-3	V
			---	---	---	$\text{mV}/^\circ\text{C}$

**Dynamic and switching Characteristics**

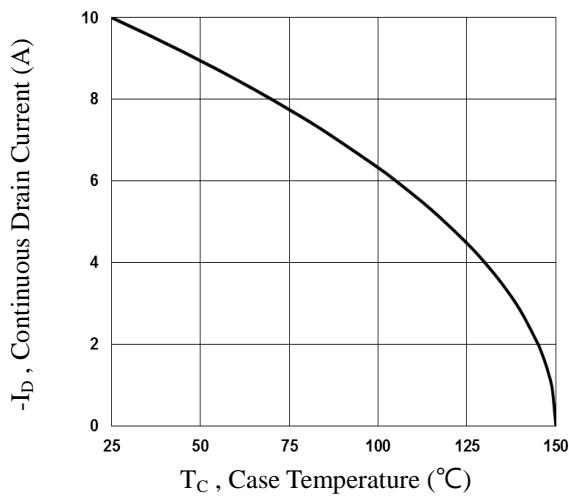
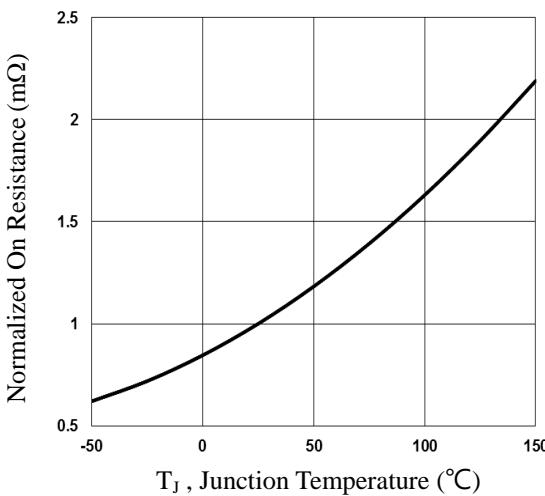
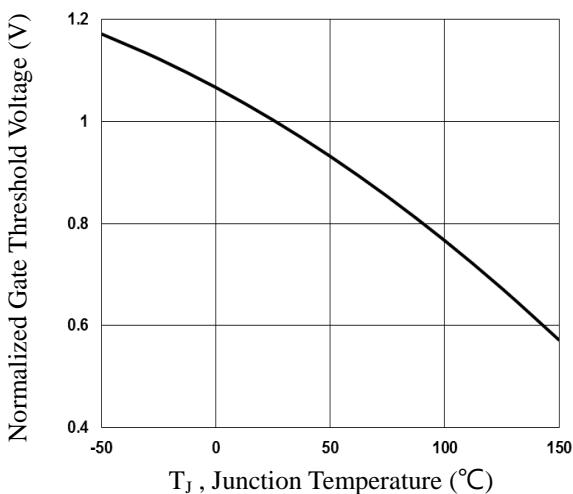
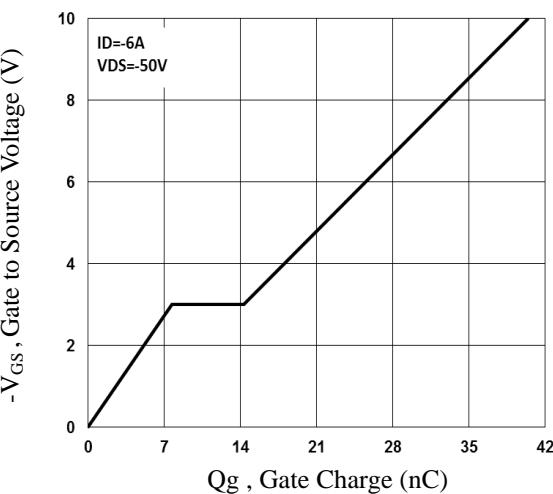
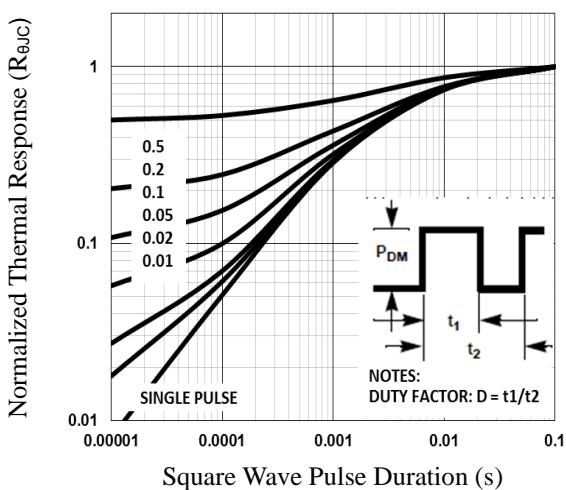
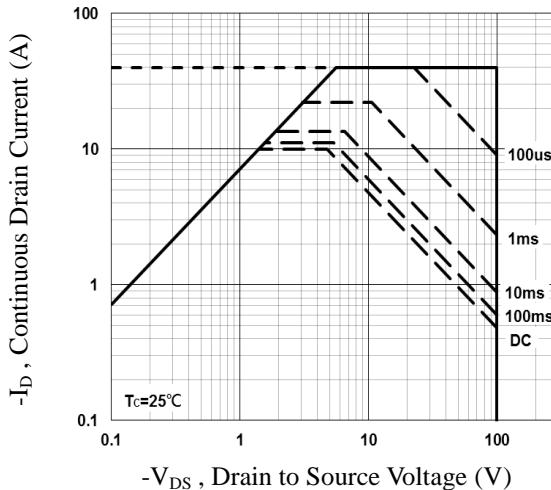
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-6\text{A}$	---	40.4	70	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	7.7	15	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	6.6	13	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=-30\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_{\text{G}}=6\Omega$ $I_{\text{D}}=-1\text{A}$	---	27	54	ns
$T_r$	Rise Time <sup>2,3</sup>		---	12	24	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	150	300	
$T_f$	Fall Time <sup>2,3</sup>		---	45	90	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	2250	3900	pF
$C_{\text{oss}}$	Output Capacitance		---	130	250	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	90	180	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	10	---	$\Omega$

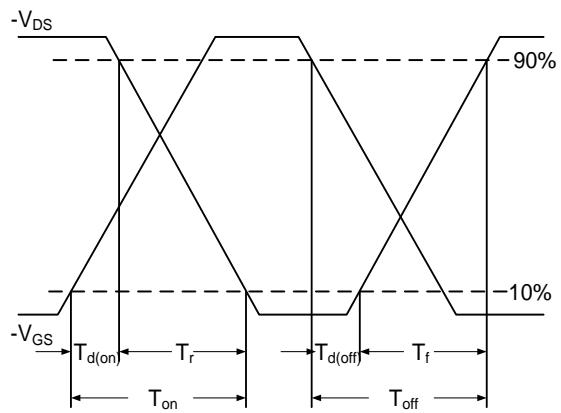
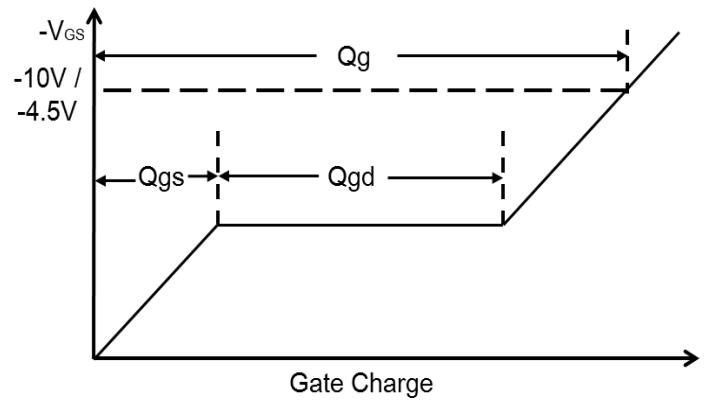
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-22	A
			---	---	-88	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.1	V
			---	---	---	ns
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	---	---	---	ns
			---	---	---	$\mu\text{C}$

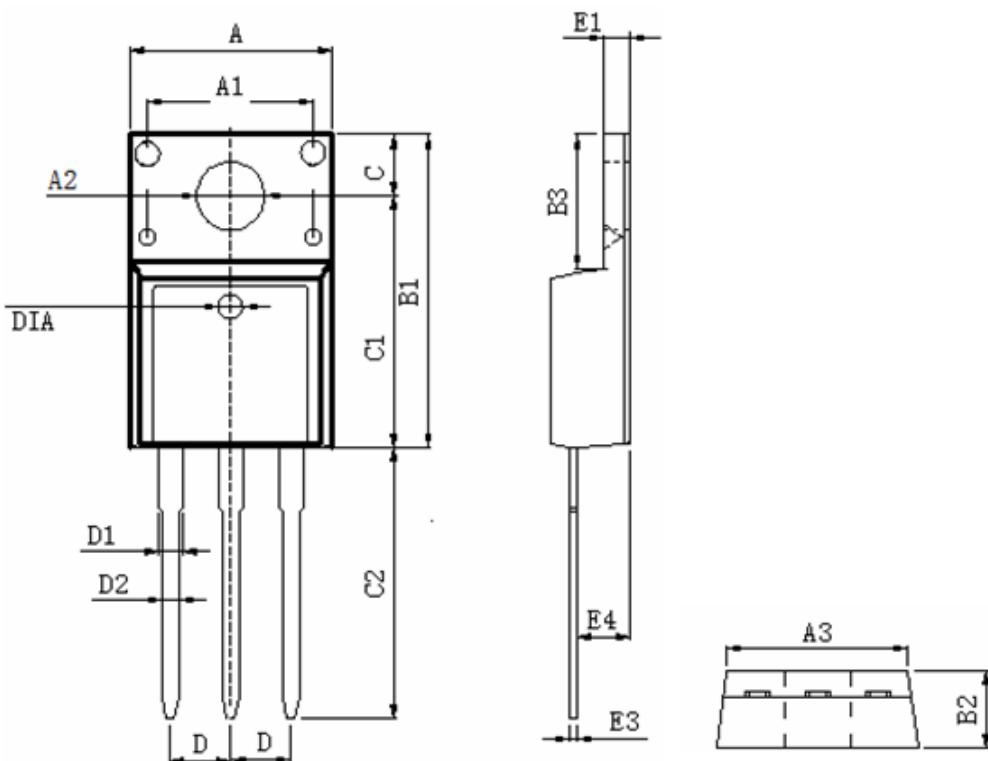
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>C</sub>**

**Fig.2 Normalized RDS(on) vs. T<sub>J</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** Gate Charge Waveform

## TO220F PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	<b>10.460</b>	<b>9.860</b>	<b>0.412</b>	<b>0.388</b>
A1	<b>7.100</b>	<b>6.900</b>	<b>0.280</b>	<b>0.272</b>
A2	<b>3.500</b>	<b>3.100</b>	<b>0.138</b>	<b>0.122</b>
A3	<b>9.900</b>	<b>9.500</b>	<b>0.390</b>	<b>0.374</b>
B1	<b>16.170</b>	<b>15.570</b>	<b>0.637</b>	<b>0.613</b>
B2	<b>4.900</b>	<b>4.500</b>	<b>0.193</b>	<b>0.177</b>
B3	<b>6.880</b>	<b>6.480</b>	<b>0.271</b>	<b>0.255</b>
C	<b>3.500</b>	<b>3.100</b>	<b>0.138</b>	<b>0.122</b>
C1	<b>12.870</b>	<b>12.270</b>	<b>0.507</b>	<b>0.483</b>
C2	<b>13.380</b>	<b>12.580</b>	<b>0.527</b>	<b>0.495</b>
D	<b>2.590</b>	<b>2.490</b>	<b>0.102</b>	<b>0.098</b>
D1	<b>1.470</b>	<b>1.070</b>	<b>0.058</b>	<b>0.042</b>
D2	<b>0.900</b>	<b>0.700</b>	<b>0.035</b>	<b>0.028</b>
E1	<b>2.740</b>	<b>2.340</b>	<b>0.108</b>	<b>0.092</b>
E3	<b>0.600</b>	<b>0.400</b>	<b>0.024</b>	<b>0.016</b>
E4	<b>2.960</b>	<b>2.560</b>	<b>0.117</b>	<b>0.101</b>
DIA	<b>Φ1.5 TYP.</b>	<b>deep0.1 TYP.</b>	<b>Φ0.059 TYP.</b>	<b>deep0.004 TYP.</b>